



Data Sheet

Customer: _____

Part No: _____

CLD-2821APG-11

Sample No: _____

Description: _____

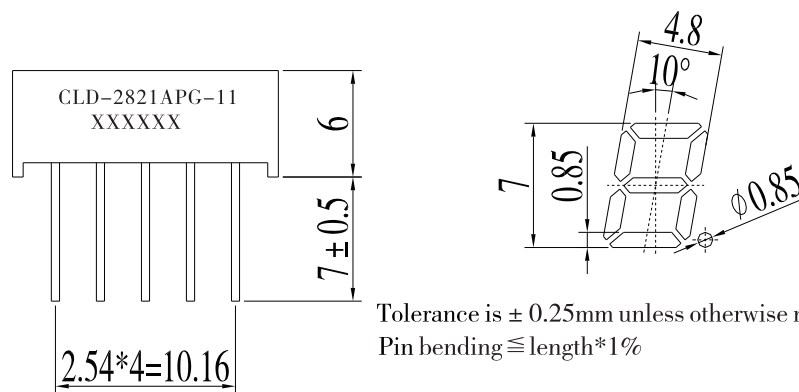
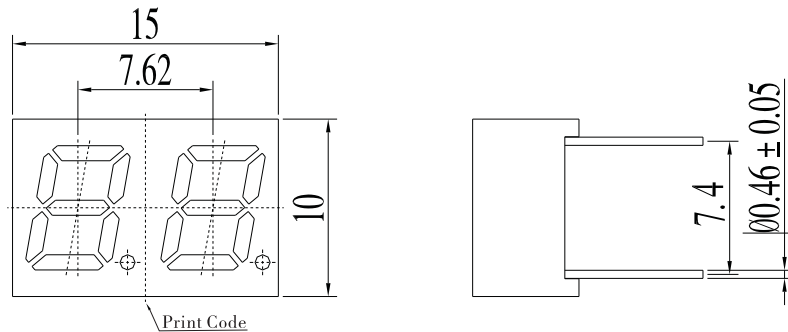
0.28 inch 2 Digit Green Color

Item No: _____

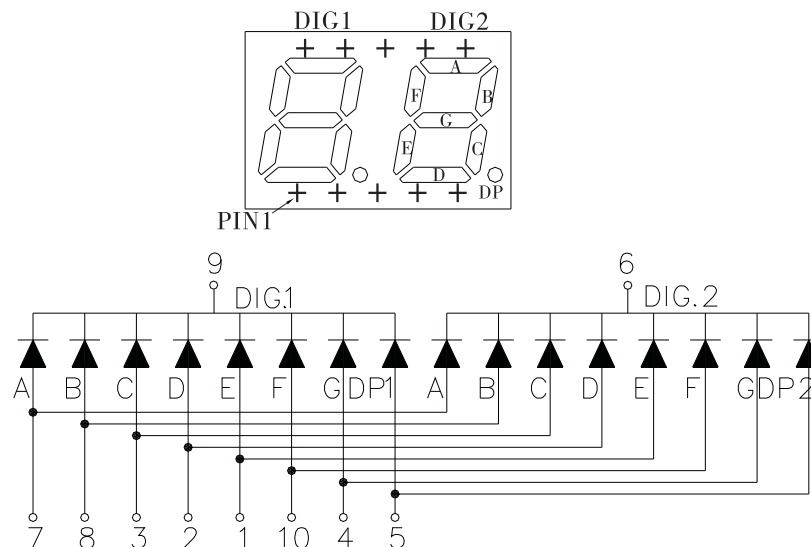
Customer			
Check	Inspection	Approval	Date

Descriptions

1. Emitting color: Pure Green
2. Lens color: White Diffused
3. Surface black color : Black
4. Dice material: InGaN/GaN

Outline drawing


Tolerance is $\pm 0.25\text{mm}$ unless otherwise noted, Unit=mm
 Pin bending \cong length*1%

Internal Circuit Diagram (C.C.)


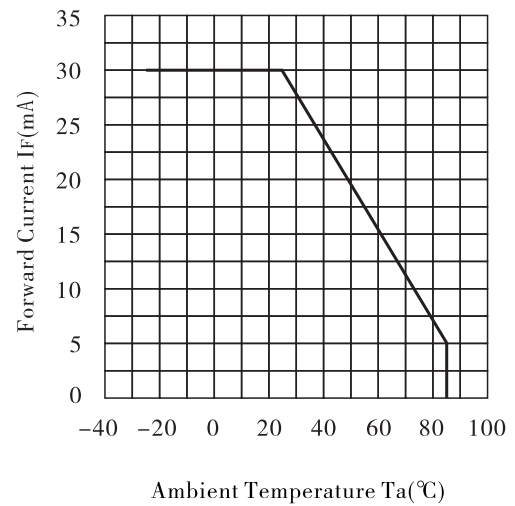
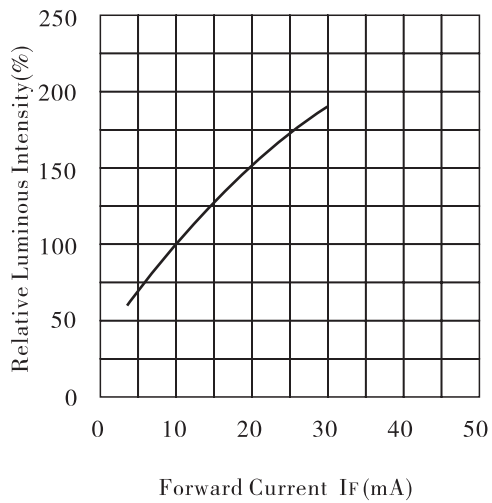
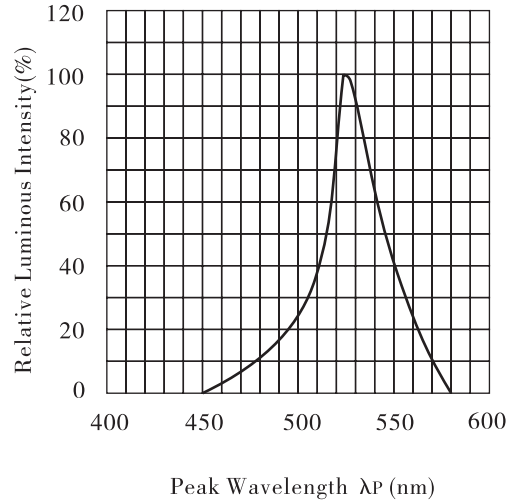
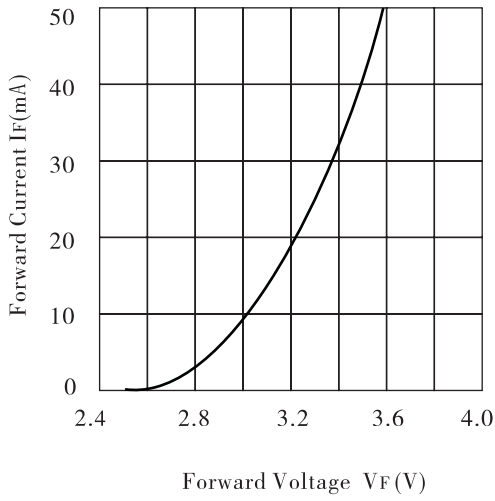
Electrical optical characteristics (Ta=25°C)

Parameter	Symbol	Pure Green			Unit	Test Condition
		Min	Typ	Max		
Forward Voltage	V _F	---	3.2	3.6	V	IF=20mA
Luminous Intensity	I _V	13.7	26.6	---	mcd	IF=10mA
Peak Wavelength	λ _P	---	525	---	nm	IF=20mA
Dominant Wavelength	λ _d	---	520	---	nm	IF=20mA
Spectral Line half-width	Δλ	---	30	---	nm	IF=20mA
Reverse Leakage Current	I _R	---	---	50	μA	VR=5V

Absolute Maximum Parameters(Ta=25°C)

Parameter	Symbol	Condition	Rating	Unit
Power Dissipation	P _D	---	120	mW
Reverse Voltage	V _R	---	5	V
Forward Average Current	I _F	---	30	mA
Temperature Coefficient	I/C	---	0.4	mA/°C
Pulse Current	I _{FP}	Duty=1/10,1kHz	100	mA
Operating Temperature Range	T _{opr}	---	-25 ~ +85	°C
Storage Temperature Range	T _{stg}	---	-30 ~ +100	°C
Soldering Condition	T _{sd}	---	260°C/5sec	°C

Typical Electro–Optical characteristic curves (Ta=25°C)



Reliability test conditions

Test Item	Test Condition	Result	Judgment criteria
Consecutive operating life test	IF=20mA, T=25°C, t=168h	0/12	Forward Voltage $V_F(V) = \text{Upper Limit} \times 1.2$ Reverse Leakage Current $I_R(\mu A) = \text{Upper Limit} \times 2.0$ Luminous Intensity I_v (mcd) = Lower Limit $\times 0.7$
High temperature storage life test	T=100°C, t=168h	0/12	
Low temperature storage life test	T=-25°C, t=168h	0/12	
high Temperature humidity storage life test	T=85 ± 2°C, RH=85% ± 3, t=168h	0/12	
Temperature cycle test	-25°C~25°C~100°C, 30min 5min 30min 10cycles	0/12	
Thermal shock test	100°C 0°C 5min 5min 20 cycles	0/12	
Soldering heat test	T=260 ± 5°C, t=10s ± 1s	0/12	
Solderability test	T=230 ± 5°C, t=5s ± 0.5s	0/12	Steeped Part ≥ 95%
Fall test	h=100cm, Free fall, 3times	0/12	Intact
Terminal strength test	W=9.8N, t=30 ± 5s	0/12	
Lead Bending test	W=4.9N, 2times	0/12	